## PMP4467 BOM

Item #	Quantity	Designator	Description	Value	Size	Part number	MFR
1	1	C1	Capacitor, Ceramic	0.1uF	0603	STD	STD
2	2	C8, C81	Capacitor, Ceramic	47uF	1206	STD	STD
3	1	C2	Capacitor, Ceramic	10uF	1210	STD	STD
4	1	C4	Capacitor, Ceramic	10nF	0603	STD	STD
5	2	C5, C62	Capacitor, Ceramic	NA	0603	STD	STD
6	1	C61	Capacitor, Ceramic	3.3nF	0603	STD	STD
7	1	D1	DIODE SCHOTTKY 40V 2A SMB	SS24	SMB	SS24T3G	Onsemi
8	1	JP1	CONN HEADER 3 POS RA 2.54			61300311021	Wurth
9	1	L1	Shielded Power Inductors	22uH	8mm*8mm	LPS8045B-223MR	Coilcraft
10	2	R1, R51	Resistor, Chip, 1/10W, 1%	0	0603	STD	STD
11	1	R8	Resistor, Chip, 1/10W, 1%	51	0603	STD	STD
12	1	R3	Resistor, Chip, 1/10W, 1%	100K	0603	STD	STD
13	1	R6	Resistor, Chip, 1/10W, 1%	33K	0603	STD	STD
14	1	R52	Resistor, Chip, 1/10W, 1%	3.9K	0603	STD	STD
15	1	U1	6.5V to 28V Input, 5V Fixed Output at 1A Step- Down Regulator with Intregrated MosFET	TPS5405	SO-8	TPS5405D	TI

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